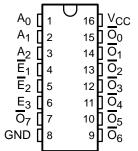
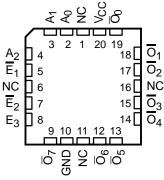
- **Function, Pinout, and Drive Compatible** With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of **Equivalent FCT Functions**
- **Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics**
- I_{off} Supports Partial-Power-Down Mode Operation
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- **Dual 1-of-8 Decoder With Enables**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- CY54FCT138T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT138T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

CY54FCT138T . . . D PACKAGE CY74FCT138T...Q OR SO PACKAGE (TOP VIEW)



CY54FCT138T...L PACKAGE (TOP VIEW)



NC - No internal connection

description

The 'FCT138T devices are 1-of-8 decoders. These devices accept three binary weighted inputs (A₀, A₁, A₂) and, when enabled, provide eight mutually exclusive active-low outputs $(\overline{O}_0 - \overline{O}_7)$. The 'FCT138T devices feature three enable inputs: two active low $(\overline{E}_1, \overline{E}_2)$ and one active high (E_3) .

All outputs are high unless \overline{E}_1 and \overline{E}_2 are low and E_3 is high. This multiple-enable function allows easy parallel expansion of the device to a 1-of-32 (five lines to 32 lines) decoder with just four 'FCT138T devices and one inverter.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	DESCRIPTION
Α	Address inputs
$\overline{E}_1, \overline{E}_2$	Enable inputs (active low)
E ₃	Enable input (active high)
Ō	Outputs



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



processing does not necessarily include testing of all pa

ORDERING INFORMATION

TA	PACI	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP – Q	Tape and reel	5	CY74FCT138CTQCT	FT138-3
	SOIC - SO Tube		5	CY74FCT138CTSOC	FCT138C
	3010 = 30	Tape and reel	5	CY74FCT138CTSOCT	FC1136C
–40°C to 85°C	QSOP - Q	Tape and reel	5.8	CY74FCT138ATQCT	FT138-1
	SOIC - SO	Tube	5.8	CY74FCT138ATSOC	FCT138A
	3010 = 30	Tape and reel	5.8	CY74FCT138ATSOCT	FOTTSOA
	QSOP – Q	Tape and reel	9	CY74FCT138TQCT	FT138
	LCC – L	Tube	6	CY54FCT138CTLMB	
–55°C to 125°C	LCC - L Tube		12	CY54FCT138TLMB	
	CDIP – D	Tube	12	CY54FCT138TDMB	·

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

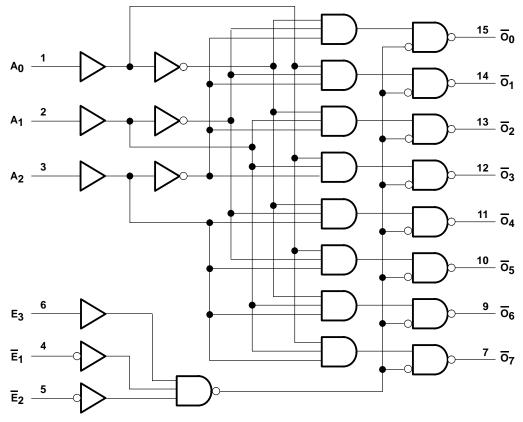
FUNCTION TABLE

		INP	UTS						OUTI	PUTS			
E ₁	E ₂	E ₃	A ₀	A ₁	A ₂	O ₀	01	02	03	04	05	06	07
Н	Х	Χ	Χ	Χ	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	Н	X	X	Χ	X	Н	Н	Н	Н	Н	Н	Н	Н
X	Χ	L	Χ	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
L	L	Н	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	L	Н	Н	L	L	Н	L	Н	Н	Н	Н	Н	Н
L	L	Н	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
L	L	Н	Н	Н	L	Н	Н	Н	L	Н	Н	Н	Н
L	L	Н	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н
L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
L	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

H = High logic level, L = Low logic level, X = Don't care



logic diagram (positive logic)



Pin numbers shown are for the D, Q, and SO packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	. −0.5 V to 7 V
DC input voltage range	. −0.5 V to 7 V
DC output voltage range	0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	90°C/W
SO package	
Ambient temperature range with power applied, T _A –	-65°C to 135°C
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 2)

		CY	4FCT13	8T	CY	74FCT13	8T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
loh	High-level output current			-12			-32	mA
lOL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	C	/54FCT13	188	CY	74FCT13	8T	LINIT
PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$		-0.7	-1.2				V
VIK	$V_{CC} = 4.75 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$					-0.7	-1.2	V
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$	2.4	3.3					
Voн	V _{CC} = 4.75 V I _{OH} = -32 mA				2			V
	$I_{OH} = -15 \text{ mA}$				2.4	3.3		
VOL	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$		0.3	0.55				V
VOL	$V_{CC} = 4.75 \text{ V}, \qquad I_{OL} = 64 \text{ mA}$					0.3	0.55	V
V_{hys}	All inputs		0.2			0.2		٧
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$			5				μA
ΙΙ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = V_{CC}$						5	μΑ
lu .	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			±1				μA
ΉΗ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						±1	μΑ
lu.	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$			±1				μA
IΙL	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						±1	μΛ
1+	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$	-60	-120	-225				mA
los‡	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$				-60	-120	-225	ША
l _{off}	$V_{CC} = 0 \text{ V}, \qquad V_{OUT} = 4.5 \text{ V}$			±1			±1	μΑ
loo	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$	/	0.1	0.2				mA
Icc	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$	/				0.1	0.2	IIIA
Aloo	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}$, $f_1 = 0$, Outputs open		0.5	2				mA
ΔICC	$V_{CC} = 5.25 \text{ V}, V_{IN} = 3.4 \text{ V}, f_1 = 0, \text{ Outputs open}$					0.5	2	IIIA
J ¶	V_{CC} = 5.5 V, Outputs open, One bit switching at 50% du cycle, $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V	ty	0.06	0.12				mA/
^I CCD [¶]	V_{CC} = 5.25 V, Outputs open, One bit switching at 50% duty cycle, $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V					0.06	0.12	MHz

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

[§] Per TTL-driven input ($V_{IN} = 3.4 \text{ V}$); all other inputs at V_{CC} or GND

This parameter is derived for use in total power-supply calculations.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER		TEST CONDITION	ie.	CY	54FCT13	8T	CY.	74FCT13	8T	UNIT
PARAMETER		CONDITION	N 5	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
	$V_{CC} = 5.5 \text{ V},$ Outputs open, Switch \overline{E}_1 , \overline{E}_2 , or	One output switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
IC#	E ₃	at 50% duty cycle	V _{IN} = 3.4 V or GND		1	2.4				mA
I.C.	$V_{CC} = 5.25 \text{ V},$ Outputs open, Switch \overline{E}_1 , \overline{E}_2 , or	One output switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	E ₃	at 50% duty cycle	V _{IN} = 3.4 V or GND					1	2.4	
C _i					5	10		5	10	pF
Co					9	12		9	12	pF

 $[\]overline{\dagger}$ Typical values are at V_{CC} = 5 V, T_A = 25°C.

Where:

IC = Total supply current

I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the ICC formula.

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY54FC	T138T	CY54FC1	Г138CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	А	ō	1.5	12	1.5	6	ns
t _{PHL}	A	O	1.5	12	1.5	6	115
^t PLH	FF	ō	1.5	12.5	1.5	6.1	ns
t _{PHL}	\overline{E}_1 or \overline{E}_2	O	1.5	12.5	1.5	6.1	110
^t PLH	Eo	ō	1.5	12.5	1.5	6.1	nc
^t PHL	E3	J	1.5	12.5	1.5	6.1	ns

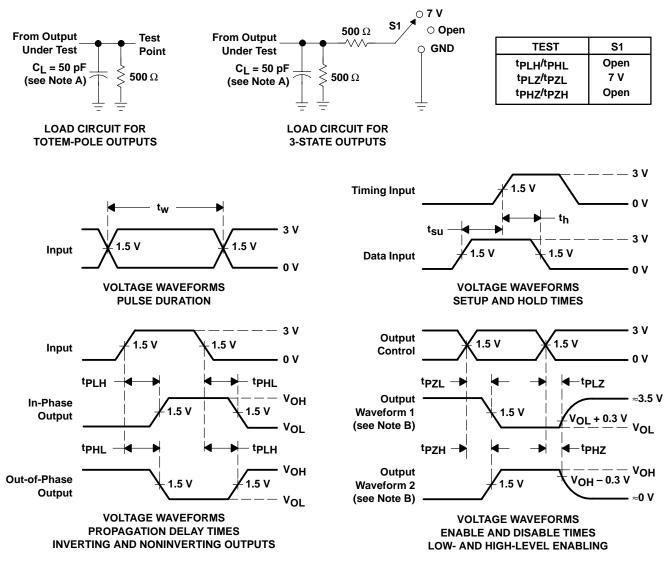
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FC	T138T	CY74FC	Г138АТ	CY74FC1	138CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNII
^t PLH	А	ō	1.5	9	1.5	5.8	1.5	5	ns
tPHL	A	O	1.5	9	1.5	5.8	1.5	5	113
t _{PLH}	EE	ō	1.5	9	1.5	5.9	1.5	5	no
tPHL	\overline{E}_1 or \overline{E}_2	O	1.5	9	1.5	5.9	1.5	5	ns
^t PLH	Ea		1.5	9	1.5	5.9	1.5	5	no
tPHL	E3	ō	1.5	9	1.5	5.9	1.5	5	ns



 $^{^{\#}}$ IC = ICC + \triangle ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9223302M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223302M2A CY54FCT 138TLMB	Samples
5962-9223302MEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223302ME A CY54FCT138TDMB	Samples
5962-9223306M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223306M2A CY54FCT 138CTLMB	Samples
5962-9223306MEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223306ME A	Samples
CY54FCT138CTLMB	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223306M2A CY54FCT 138CTLMB	Samples
CY54FCT138TDMB	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223302ME A CY54FCT138TDMB	Samples
CY54FCT138TLMB	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223302M2A CY54FCT 138TLMB	Samples
CY74FCT138ATQCT	ACTIVE	SSOP	DBQ	16	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FT138-1	Samples
CY74FCT138ATSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT138A	Samples
CY74FCT138ATSOCG4	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT138A	Samples
CY74FCT138ATSOCT	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT138A	Samples
CY74FCT138CTQCT	ACTIVE	SSOP	DBQ	16	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FT138-3	Samples
CY74FCT138CTSOC	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT138C	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT138TQCT	ACTIVE	SSOP	DBQ	16	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FT138	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT138ATQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
CY74FCT138ATSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
CY74FCT138CTQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
CY74FCT138TQCT	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT138ATQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6
CY74FCT138ATSOCT	SOIC	DW	16	2000	350.0	350.0	43.0
CY74FCT138CTQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6
CY74FCT138TQCT	SSOP	DBQ	16	2500	340.5	338.1	20.6

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9223302M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9223306M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
CY54FCT138CTLMB	FK	LCCC	20	55	506.98	12.06	2030	NA
CY54FCT138TLMB	FK	LCCC	20	55	506.98	12.06	2030	NA
CY74FCT138ATSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6
CY74FCT138ATSOCG4	DW	SOIC	16	40	506.98	12.7	4826	6.6
CY74FCT138CTSOC	DW	SOIC	16	40	506.98	12.7	4826	6.6

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